N-Channel 30-V (D-S) MOSFET

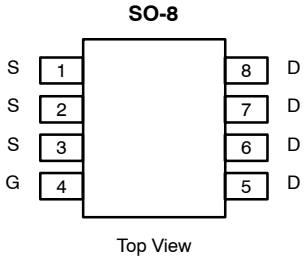
PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
30	0.0125 @ V_{GS} = 10 V	11
	0.014 @ V_{GS} = 4.5 V	10

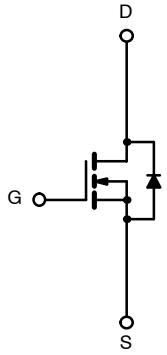
FEATURES

- TrenchFET® Gen II Power MOSFET

APPLICATIONS

- High-Side DC/DC Conversion
  - Notebook
  - Desktop
  - Server
- Notebook Logic DC/DC, Low-Side





Ordering Information: Si4348DY—E3 (Lead Free)
Si4348DY-T1—E3 (Lead Free with Tape and Reel)

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C UNLESS OTHERWISE NOTED)					
Parameter		Symbol	10 secs	Steady State	Unit
Drain-Source Voltage		V_{DS}	30		V
Gate-Source Voltage		V_{GS}	±12		
Continuous Drain Current (T_J = 150°C)[a]	T_A = 25°C	I_D	11	8.0	A
	T_A = 70°C		8.9	6.5	
Pulsed Drain Current		I_{DM}	40		
Continuous Source Current (Diode Conduction)[a]		I_S	2.2	1.20	
Maximum Power Dissipation[a]	T_A = 25°C	P_D	2.5	1.31	W
	T_A = 70°C		1.6	0.84	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	–55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient[a]	t ≤ 10 sec	R_{thJA}	43	50	°C/W
	Steady State		74	95	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	19	25	

Notes
a. Surface Mounted on 1" x 1" FR4 Board.

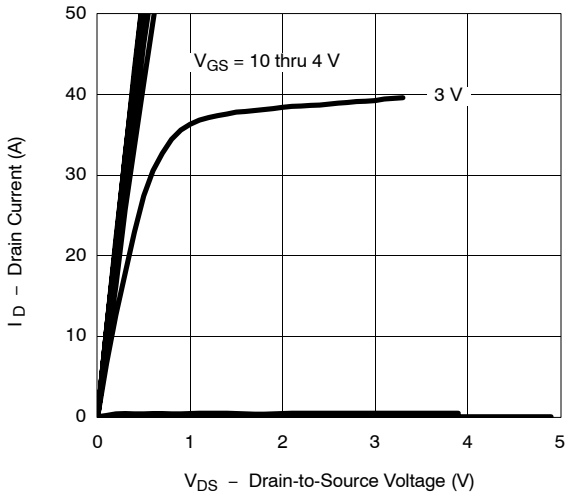
SPECIFICATIONS (T_J = 25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 μA	0.8		2.0	V
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±12 V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 30 V, V_{GS} = 0 V			1	μA
		V_{DS} = 30 V, V_{GS} = 0 V, T_J = 55°C			5	
On-State Drain Current[a]	$I_{D(on)}$	V_{DS} ≥ 5 V, V_{GS} = 10 V	30			A
Drain-Source On-State Resistance[a]	$r_{DS(on)}$	V_{GS} = 10 V, I_D = 11 A		0.0105	0.0125	Ω
		V_{GS} = 4.5 V, I_D = 10 A		0.0115	0.014	
Forward Transconductance[a]	g_{fs}	V_{DS} = 15 V, I_D = 11 A		40		S
Diode Forward Voltage[a]	V_{SD}	I_S = 2.2 A, V_{GS} = 0 V		0.75	1.1	V
Dynamic[b]						
Total Gate Charge	Q_g	V_{DS} = 15 V, V_{GS} = 4.5 V, I_D = 11 A		15	23	nC
Gate-Source Charge	Q_{gs}			5		
Gate-Drain Charge	Q_{gd}			4.3		
Gate Resistance	R_g			0.5		Ω
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 15 V, R_L = 15 Ω I_D ≅ 1 A, V_{GEN} = 10 V, R_g = 6 Ω		10	15	ns
Rise Time	t_r			11	17	
Turn-Off Delay Time	$t_{d(off)}$			55	85	
Fall Time	t_f			9	15	
Source-Drain Reverse Recovery Time	t_{rr}	I_F = 2.2 A, di/dt = 100 A/μs		22	35	

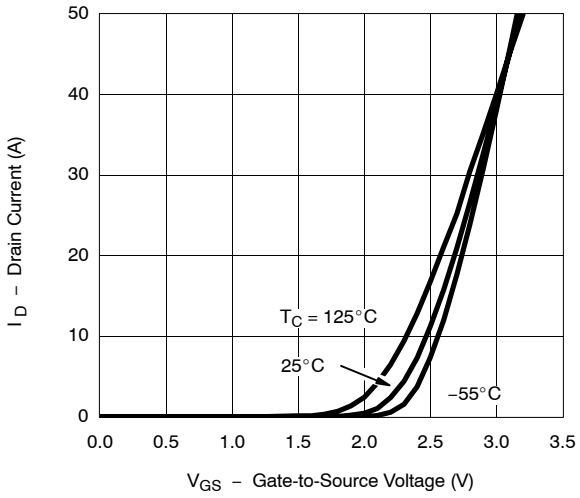
Notes
a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
b. Guaranteed by design, not subject to production testing.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

Output Characteristics

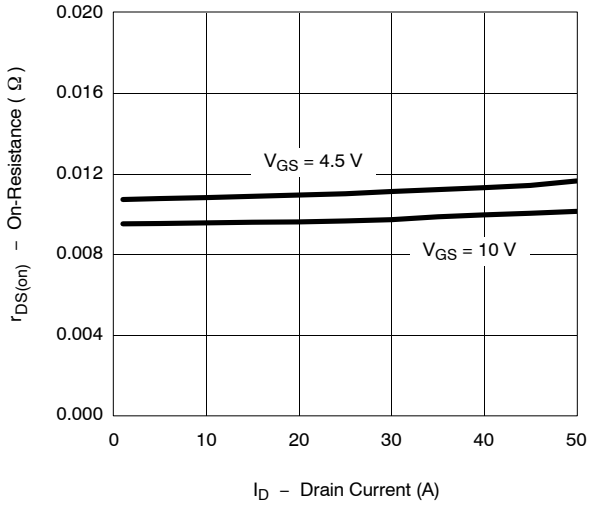


Transfer Characteristics

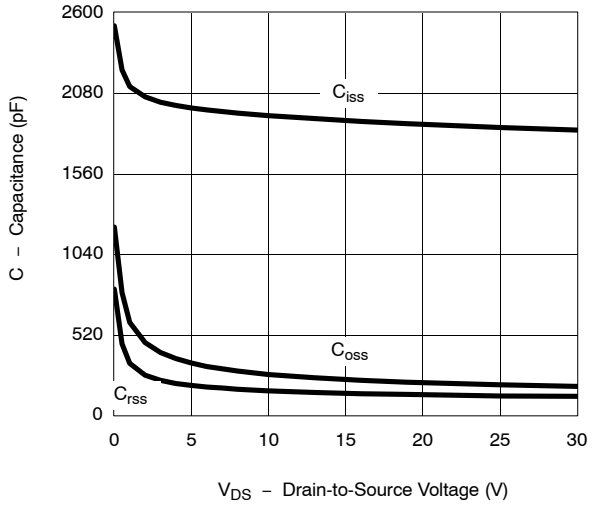


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

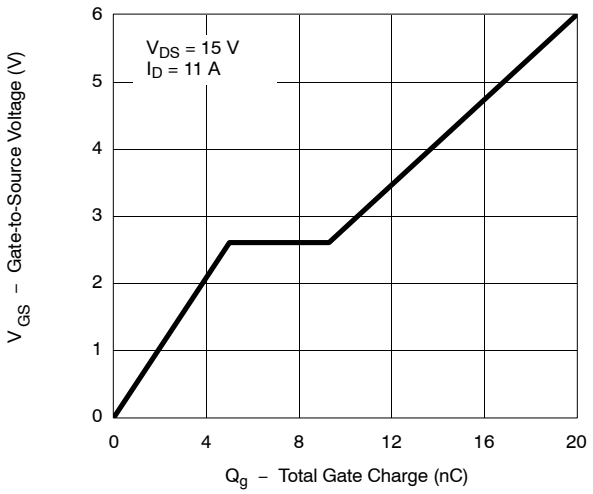
On-Resistance vs. Drain Current



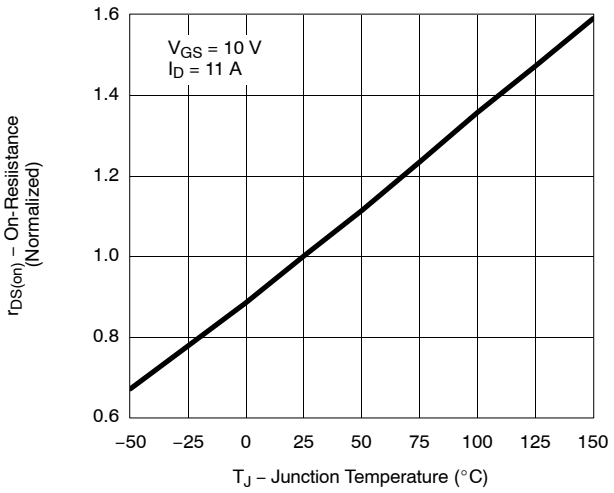
Capacitance



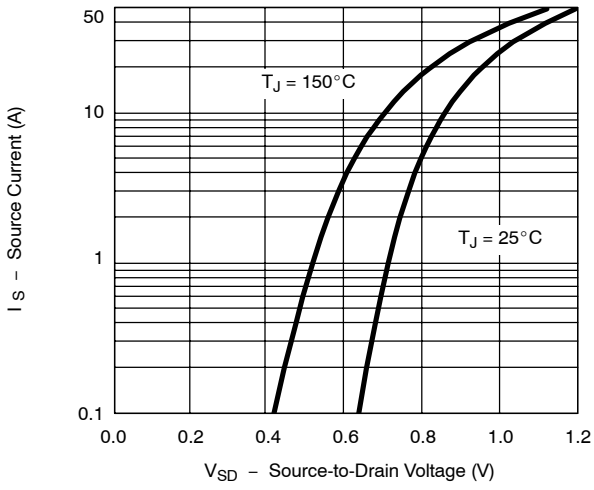
Gate Charge



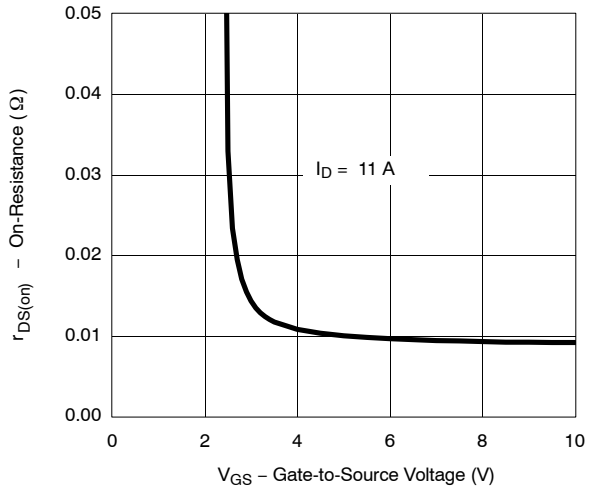
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage

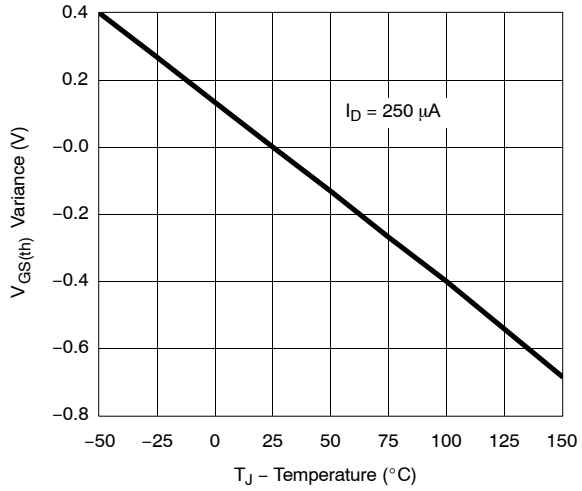


On-Resistance vs. Gate-to-Source Voltage

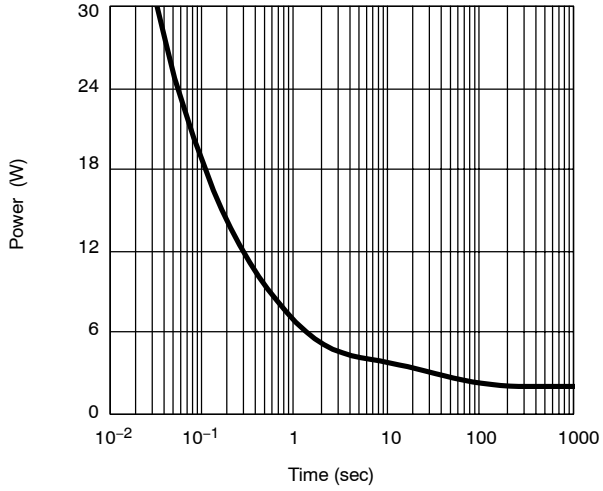


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

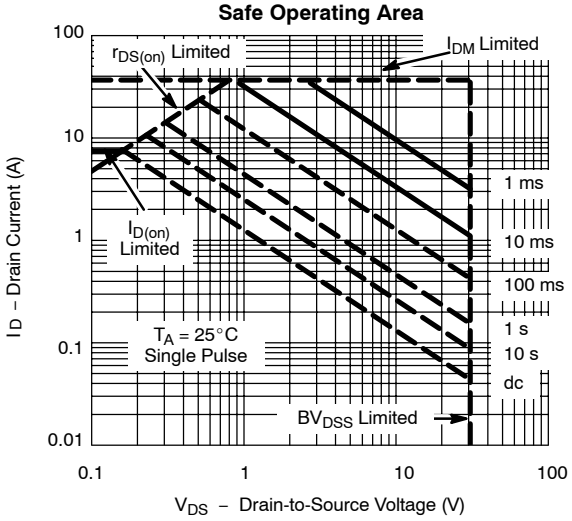
Threshold Voltage



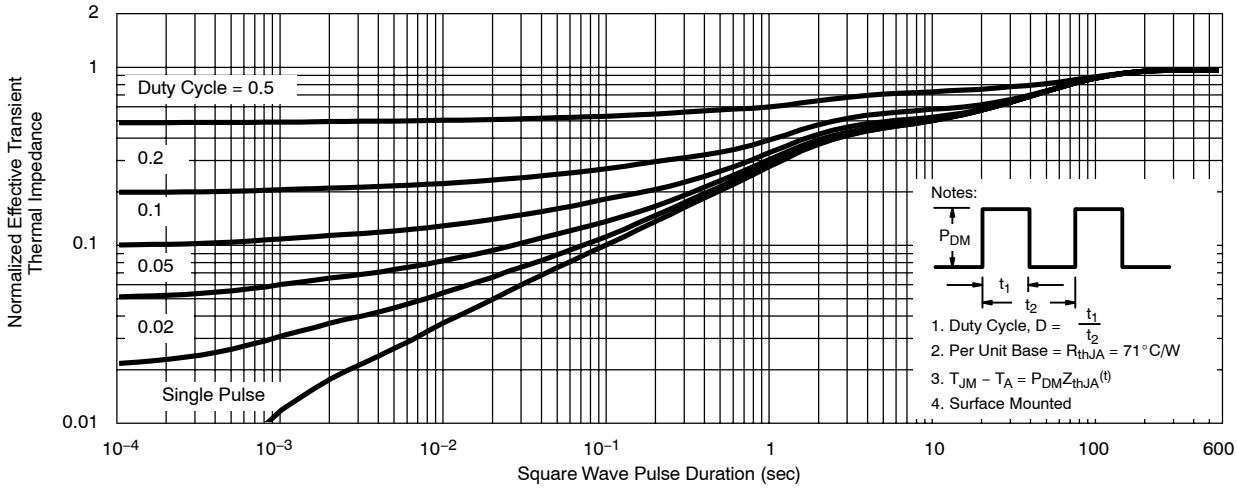
Single Pulse Power, Junction-to-Ambient



Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)